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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION of

Fallon et al.

Confirmation No. 2533

Serial No. 09/690,485

Art Unit 2827

Filed: October 17, 2000

Examiner: Jeremy C. Norris

Title: 7

TWO SIGNAL ONE POWER PLANE

CIRCUIT BOARD

Atty. Docket No. END919960138US2 (IEN-10-5202-C1)

## **DECLARATION OF ROSS W. KEESLER UNDER RULE 132**

I, ROSS W. KEESLER, declare as follows:

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MAR 1 2 2002

1. I am one of the inventors in the above-entitled application.

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- 2. I received a BS degree in Chemical Engineering from Cornell University in Ithaca, New York in 1979.
- 3. I have been employed at IBM Corporation since 1979 in various capacities in Metallized Ceramic Substrate Manufacturing Engineering and Panel / Laminate Chip Carrier Process Development, an advisory engineer in photolithography process engineering, my present position being an Advisory Engineer in Laminate Chip Carriers Process Engineering.
- 4. I am familiar with polyimides and I am perticularly familiar with polyimides used by International Business Machines Corporation and even more specific to polyimides used by the Endicott site of the IBM Corporation.

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- To my knowledge, there are both photoimageable polyimides and non-5. photoimageable polyimides. There are different types of non-photoimageable polyimides.
- To the best of my knowledge and belief, no photoimageable polyimides have 6. been used in packaging structures developed by the IBM Endicott site. Although there have been occasional experiments with photoimageable polyimides, none of these has resulted in a commercial product, and non-photoimageable polyimides are the only polyimides which have ever been used in a commercial product from the Endicott site.
- To the best of my knowledge and belief, no photoimageable polyimides have been used in chip packaging implementations commercially for packages developed by any IBM site in which polyimide packaging structure have been developed.

I declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. §101, and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Date: 3/12/02

Ross W. Keesler

ROSS W. KEESLER

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